

N-Channel Trench Power MOSFET

General Description

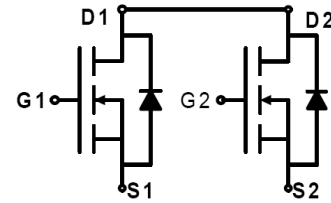
The CS8205E uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching applications.

Features

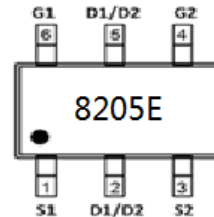
- $V_{DS} = 19.5V, I_D = 4.2A$
 $R_{DS(ON)} < 26m\Omega @ V_{GS} = 4.5V$
 $R_{DS(ON)} < 36m\Omega @ V_{GS} = 2.5V$
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

Application

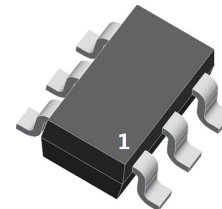
- Battery protection
- Load switch
- Power management



Schematic Diagram



Marking and pin Assignment



SOT23-6 top view

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|---------|----------------|-----------|------------|------------|
| 8205E | CS8205E | SOT23-6 | Ø180mm | 8mm | 3000 units |

Table 1. Absolute Maximum Ratings ($T_A = 25^\circ C$)

| Symbol | Parameter | Value | Unit |
|------------------|---|------------|------------|
| V_{DS} | Drain-Source Voltage ($V_{GS} = 0V$) | 19.5 | V |
| V_{GS} | Gate-Source Voltage ($V_{DS} = 0V$) | ± 10 | V |
| I_D | Drain Current-Continuous | 4.2 | A |
| $I_{DM (pluse)}$ | Drain Current-Continuous@ Current-Pulsed (Note 1) | 25 | A |
| P_D | Maximum Power Dissipation | 1.25 | W |
| T_J, T_{STG} | Operating Junction and Storage Temperature Range | -55 To 150 | $^\circ C$ |

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

Table 2. Thermal Characteristic

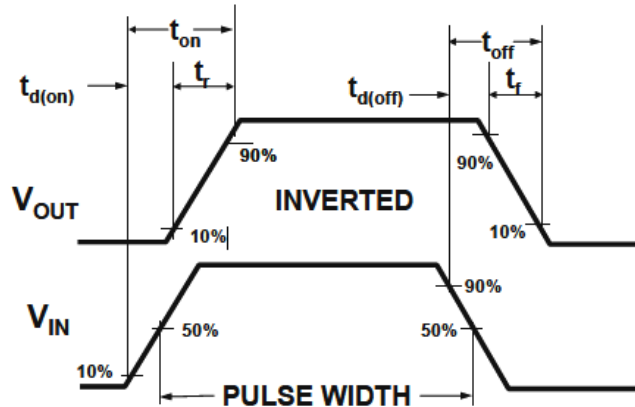
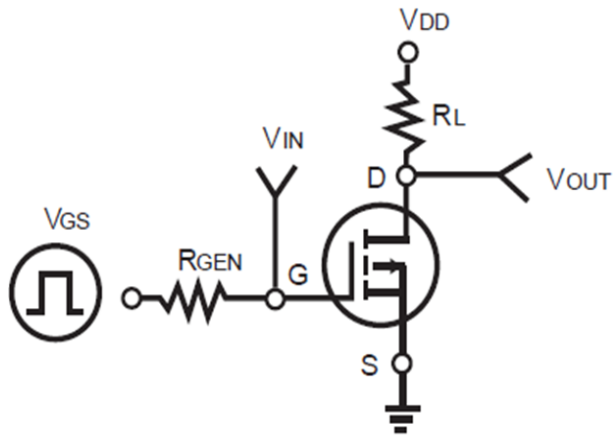
| Symbol | Parameter | Value | Unit |
|-----------------|---|-------|--------------|
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | 100 | $^\circ C/W$ |

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|--|---|------|------|-----------|------------|
| On/Off States | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=250\mu A$ | 19.5 | 21 | | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=19V, V_{GS}=0V$ | | | 1 | μA |
| I_{GSS} | Gate-Body Leakage Current | $V_{GS}=\pm 10V, V_{DS}=0V$ | | | ± 100 | nA |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_D=250\mu A$ | 0.5 | 0.65 | 1.1 | V |
| g_{FS} | Forward Transconductance | $V_{DS}=5V, I_D=4.2A$ | 4 | | | S |
| $R_{DS(ON)}$ | Drain-Source On-State Resistance | $V_{GS}=4.5V, I_D=4.2A$ | | 18 | 26 | m Ω |
| | | $V_{GS}=2.5V, I_D=3A$ | | 24 | 36 | m Ω |
| Dynamic Characteristics | | | | | | |
| C_{iss} | Input Capacitance | $V_{DS}=10V, V_{GS}=0V,$ $f=1.0MHz$ | | 450 | | pF |
| C_{oss} | Output Capacitance | | | 230 | | pF |
| C_{rss} | Reverse Transfer Capacitance | | | 110 | | pF |
| Switching Times | | | | | | |
| $t_{d(on)}$ | Turn-on Delay Time | $V_{DD}=10V, I_D=1A,$ $V_{GS}=4.5V, R_G=6\Omega$ | | 10 | | nS |
| t_r | Turn-on Rise Time | | | 11 | | nS |
| $t_{d(off)}$ | Turn-Off Delay Time | | | 34 | | nS |
| t_f | Turn-Off Fall Time | | | 30 | | nS |
| Q_g | Total Gate Charge | $V_{DS}=10V, I_D=4A, V_{GS}=4.5V$ | | 10 | | nC |
| Q_{gs} | Gate-Source Charge | | | 2.8 | | nC |
| Q_{gd} | Gate-Drain Charge | | | 1.8 | | nC |
| Source-Drain Diode Characteristics | | | | | | |
| I_{SD} | Source-Drain Current(Body Diode) | | | | 1.7 | A |
| V_{SD} | Forward on Voltage ^(Note 1) | $V_{GS}=0V, I_S=1.7A$ | | 0.79 | 1.2 | V |

Notes 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Switch Time Test Circuit and Switching Waveforms:



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

Figure1. Power Dissipation

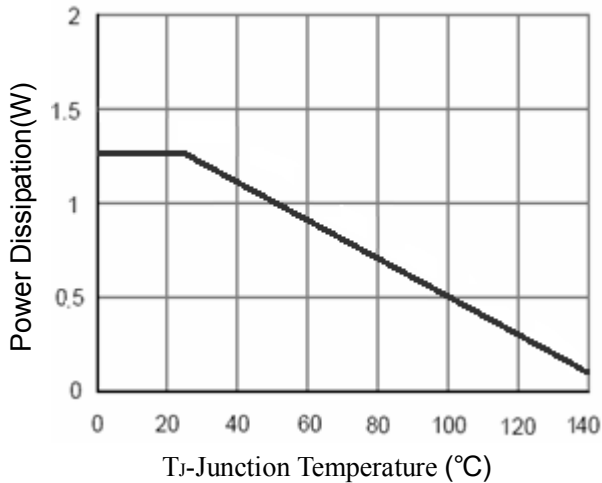


Figure2. Drain Current

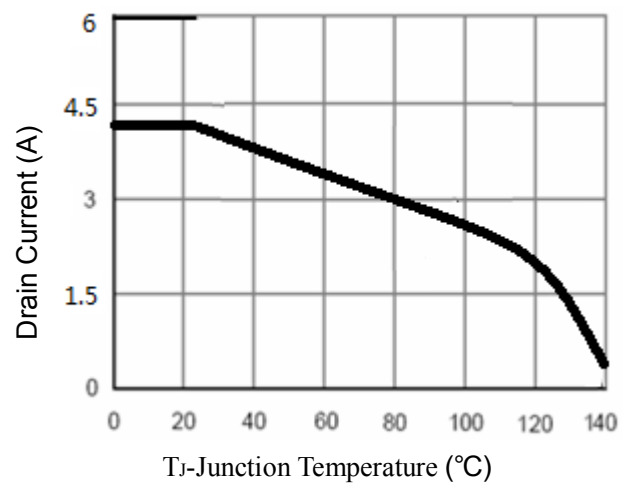


Figure3. Output Characteristics

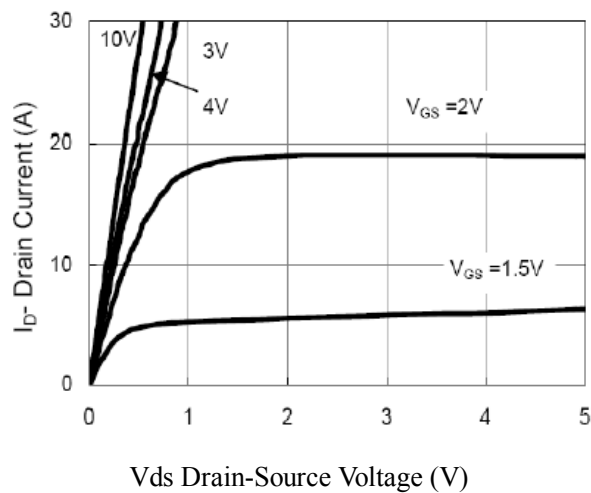


Figure4. Transfer Characteristics

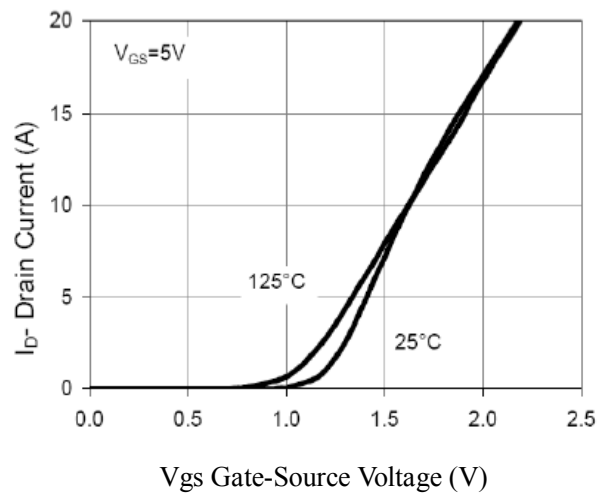


Figure5. Capacitance

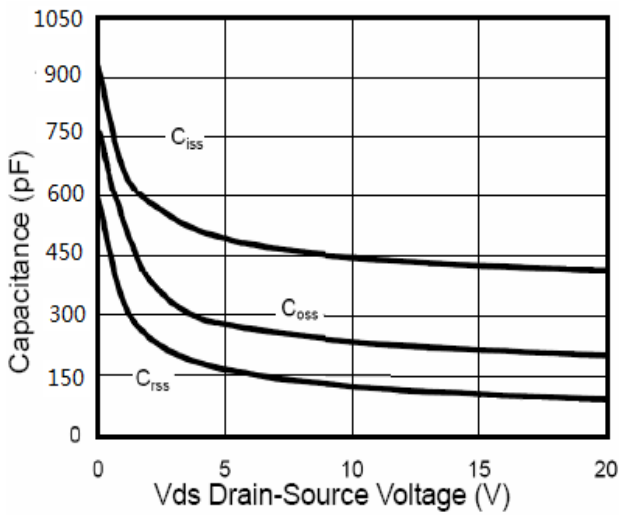


Figure6. $R_{DS(ON)}$ vs Junction Temperature

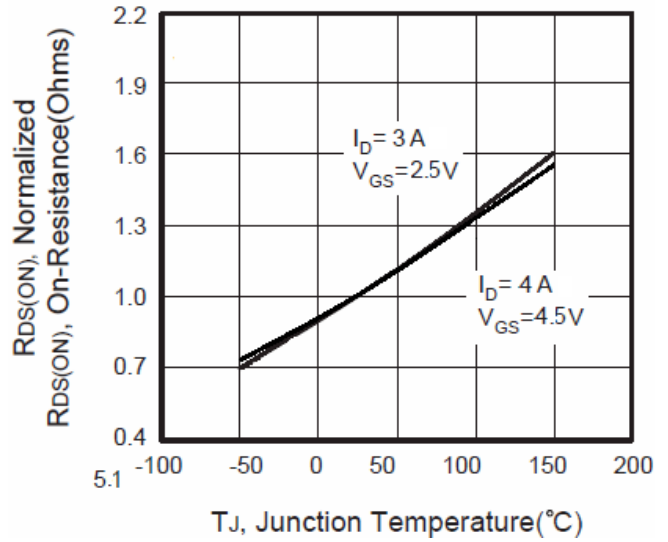


Figure7. Max BV_{DSS} vs Junction Temperature

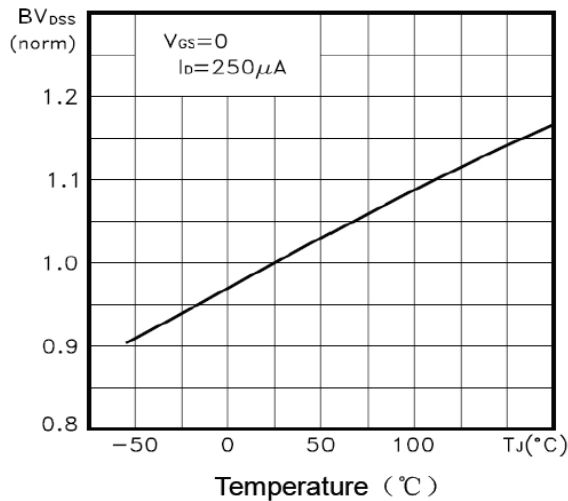


Figure8. $V_{GS(th)}$ vs Junction Temperature

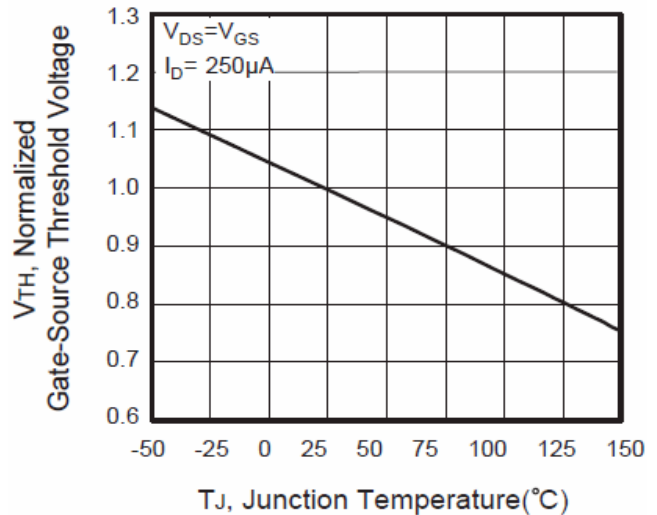


Figure9. Gate Charge Waveforms

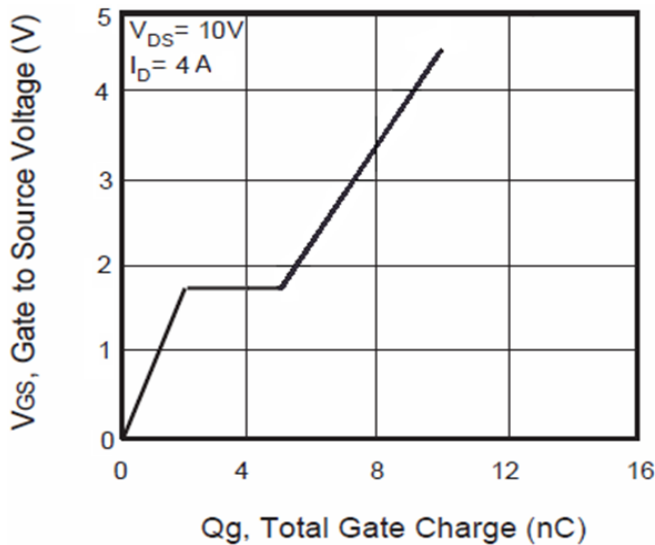


Figure10. Maximum Safe Operating Area

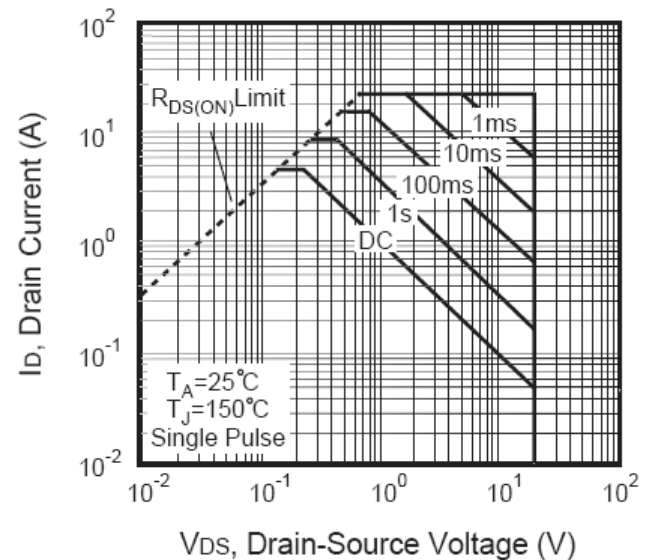
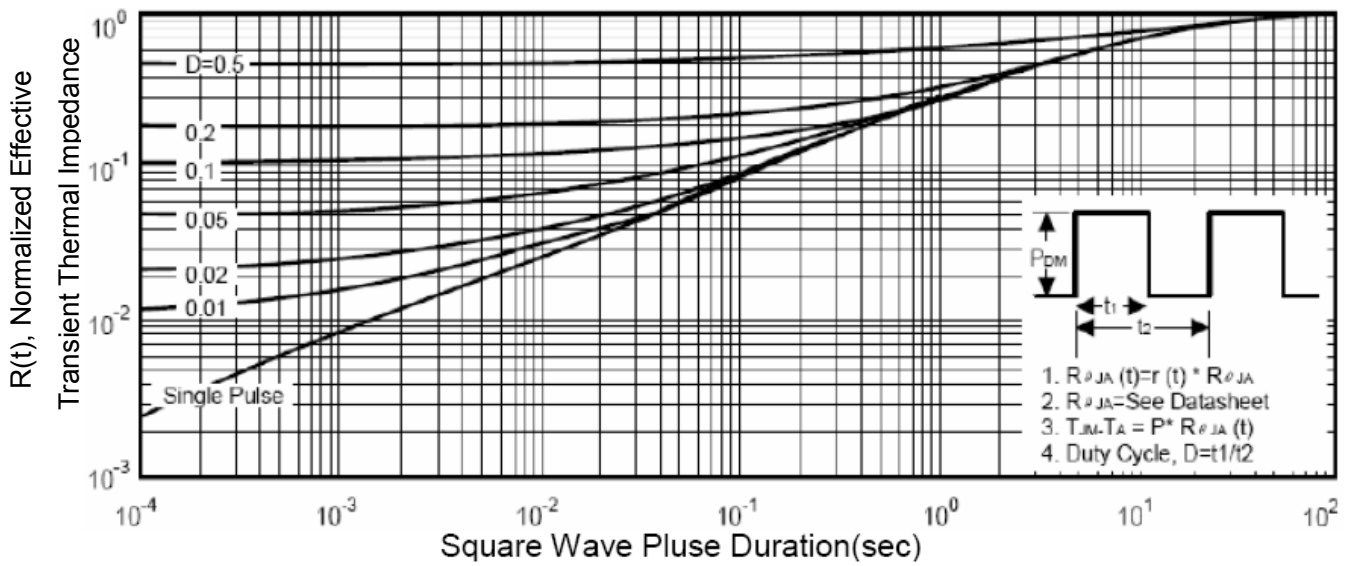
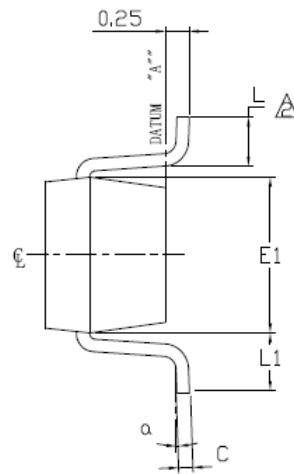
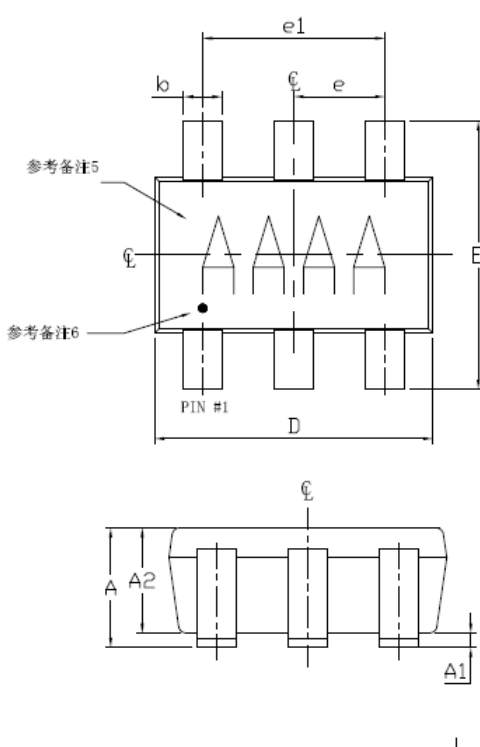


Figure11. Normalized Maximum Transient Thermal Impedance



SOT23-6 Package Information



| SYMBOL | MIN | NOM | MAX |
|--------|-----------|-------|------|
| A | 0.90 | 1.25 | 1.45 |
| A1 | 0.00 | 0.05 | 0.15 |
| A2 | 0.90 | 1.10 | 1.30 |
| b | 0.35 | 0.40 | 0.50 |
| C | 0.08 | 0.15 | 0.20 |
| D | 2.80 | 2.90 | 3.00 |
| E | 2.60 | 2.80 | 3.00 |
| E1 | 1.50 | 1.625 | 1.75 |
| L | 0.35 | 0.45 | 0.60 |
| L1 | 0.60 REF. | | |
| e1 | 1.90 BSC. | | |
| e | 0.95 BSC. | | |
| a | 0° | 2.5° | 8° |

PKG CODES:
 U6-1, U6-2, U6-4, U6CN-2,
 U6SN-1, U6F-6, U6FH-6

备注:

1. 标注单位:MM.
2. 引脚长度的测量点为引脚与塑封体接触点及引脚边缘最长处。
3. 塑封体测量尺寸不包括毛刺及金属毛刺, 另塑封体毛刺及金属毛刺长度不超过0.25mm.
4. 引脚平面度控制小于0.1mm.
5. 印字面向上进行读取时, PIN1 位于左下方 (参考图解).
6. PIN1的标记最小为 \varnothing 0.3mm, 并位于PIN1脚位上方.
7. 考文献: JEDECT0236-VARIATION AB.